



MP15-35 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu), Gold (Au)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Terminal 28.01%	Copper (Cu)	7440-50-8	4,187.650	99.979	280,952.4
	Phosphorus (P)	7723-14-0	0.042	0.0010	2.8
	Arsenic (As)	7440-38-2	0.042	0.0010	2.8
	Tin (Sn)	7440-31-5	0.042	0.0010	2.8
	Oxygen (O)	7782-44-7	0.021	0.0005	1.4
	Sulfur (S)	7704-34-9	0.503	0.0120	33.7
	Iron (Fe)	7439-89-6	0.028	0.0007	1.9
	Nickel (Ni)	7440-02-0	0.013	0.0003	0.8
	Bismuth (Bi)	7440-69-9	0.084	0.0020	5.6
	Antimony (Sb)	1309-64-4	0.084	0.0020	5.6
	Lead (Pb)	7439-92-1	0.021	0.0005	1.4
	Zinc (Zn)	7440-66-6	0.013	0.0003	0.8
	Total			4,188.54	
Solder Wafer 0.33%	Lead (Pb)	7439-92-1	44.99	92.50	3,018.5
	Tin (Sn)	7440-31-5	2.43	5.00	163.2
	Silver (Ag)	7440-22-4	1.22	2.50	81.6
Total			48.64		
Chip 0.25%	Silicon (Si)	7440-21-3	37.87	100.00	2,540.7
	Total				37.87
Case 49.56%	Epoxy	25928-94-3	3,185.50	43.13	213,717.5
	Aluminium (Al)	7429-90-5	4,201.00	56.87	281,848.1
	Total			7,386.50	
Potting 21.69%	Epoxy	25928-94-3	3,233.00	100.00	216,904.3
	Total				3,233.00
Plating 0.16%	Nickel (Ni)	7440-02-0	10.64	100.00	714.0
	Total				10.64
Total mass (mg)			14,905.19		